# Monthly LabAdviser/Process2Share update: 17/4 2015

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| Updated Subject  | Contributor | Link to the updated pages |
| **AOE**SiO2 etching results on 1-3µm structures | **Frederik Stöhr @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_AOE/Images_of_m_resist_etches#Resist_mask_baked_at_150dg_effected_by_m_res_ny> |
| **Al2O3 etching**With AOE | **Frederik Stöhr @danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_AOE#Etching_of_micro_structures_in_Aluminum_oxide> |
| AFMIncluded presentation from Re-training Marts/April 2015Changed recommendation of what workspace to use. | **Berit G. Herstrøm @danchip** | [http://labadviser.danchip.dtu.dk/index.php/Specific\_Process\_Knowledge/Characterization/AFM:\_Atomic\_Force\_Microscopy#Process\_Information](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/AFM%3A_Atomic_Force_Microscopy#Process_Information)[http://labadviser.danchip.dtu.dk/index.php/Specific\_Process\_Knowledge/Characterization/AFM:\_Atomic\_Force\_Microscopy/Workspaces](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/AFM%3A_Atomic_Force_Microscopy/Workspaces) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

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|  |  | **Manual for Aligner: MA6 - 2** |
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|  |  | **Manual for Oven: HMDS-2** |
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|  |  | **Manual for AFM Icon-PT** |
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